IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					terials and l	ials and Mfg Information			
upplier Infor												<u>.</u>			
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2025-06-05			
Contact Name			Title - Contact			I	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stev	wards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Repre	sentative*		Title - Representative			I	Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Pro			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item N	Number	Mfr Item Name			Effective Date	e Versi	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		MT9V115EBKSTC- VGA 1/13CIS SO		С		2025-06-05 CP2		CP2	10.793		mg	Each			
<b>Ianufacturin</b>	g Proccess Information	on													
Terminal Plating / Grid Array Material Termin			rminal Base Alloy J-STD-020 MSI			L Rating	Peak Process Body Temperature   Max Time at Peak			ak Temper	Temperature Number of Reflow Cycles				
SnAgCu		CU	CU Alloy 3				260	C		30	seco				
omments															
TTENTION: M	SL 3 Rated item requires l	Bake and Dry	y Pack (after	electrical test)											
or more informa	tion regarding material co	omposition pl	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.69	mg		Misc.	proprietary data		0.0064	mg
			Supplier	Silicon (Si)	7440-21-3		1.6668	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0167	mg
Die Attach	0.16	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.096	mg
			Supplier	Epoxy resins	129915-35-1		0.032	mg
			Supplier	Acrylic resins	Proprietary Data		0.032	mg
Electrode	0.18	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.1072	mg
			Supplier	Gold (Au)	7440-57-5		0.0043	mg
			Supplier	Copper (Cu)	7440-50-8		0.0027	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0657	mg
Glass Lid /Cap	7.9	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		1.1218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.95	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.896	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.869	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.0079	mg
			В	Arsenic Trioxide (As2O3)	1327-53-3		0.0553	mg
Lid Attach	0.003	mg		Photoinitiator	proprietary data		0.0008	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0022	mg
Solder Ball	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.0107	mg
			Supplier	Tin (Sn)	7440-31-5		0.1261	mg
			Supplier	Copper (Cu)	7440-50-8		0.0032	mg
Substrate and Solder Mask	0.72	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.072	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.342	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.306	mg